Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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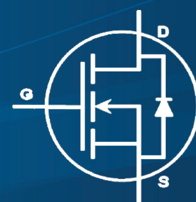
EPC2033 – Enhancement Mode Power Transistor

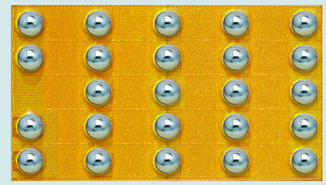
V_{DSS} , 150 V
$R_{DS(on)}$, 7 mΩ
I_D , 48 A



EFFICIENT POWER CONVERSION

RoHS Halogen-Free

Gallium Nitride is grown on Silicon Wafers and processed using standard CMOS equipment leveraging the infrastructure that has been developed over the last 60 years. GaN's exceptionally high electron mobility and low temperature coefficient allows very low $R_{DS(on)}$, while its lateral device structure and majority carrier diode provide exceptionally low Q_G and zero Q_{RR}. The end result is a device that can handle tasks where very high switching frequency, and low on-time are beneficial as well as those where on-state losses dominate.



EPC2033 eGaN® FETs are supplied only in passivated die form with solder bumps.
Die Size: 4.6 mm x 2.6 mm

- High Frequency DC-DC Conversion
- Motor Drive
- Industrial Automation
- Class-D Audio

www.epc-co.com/epc/Products/eGaNFETs/EPC2033.aspx

Maximum Ratings			
V_{DS}	Drain-to-Source Voltage (Continuous)	150	V
I_D	Continuous (T_A = 25˚C, $R_{\theta JA}$= 4˚C/W)	48	A
	Pulsed (25˚C, T_{PULSE} = 300 µs)	260	
V_{GS}	Gate-to-Source Voltage	6	V
	Gate-to-Source Voltage	-4	
T_J	Operating Temperature	-40 to 150	˚C
T_{STG}	Storage Temperature	-40 to 150	

Static Characteristics (T_J= 25˚C unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-to-Source Voltage	V_{GS} = 0 V, I_D = 0.7 mA	150			V
I_{DSS}	Drain Source Leakage	V_{DS} = 120 V, V_{GS} = 0 V		0.1	0.5	mA
I_{GSS}	Gate-to-Source Forward Leakage	V_{GS} = 5 V		1	8	mA
	Gate-to-Source Reverse Leakage	V_{GS} = -4 V		0.1	0.5	mA
$V_{GS(TH)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 9 mA	0.8	1.4	2.5	V
$R_{DS(on)}$	Drain-to-Source On Resistance	V_{GS} = 5 V, I_D = 25 A		5	7	mΩ
V_{SD}	Source-to-Drain Forward Voltage	I_S = 0.5 A, V_{GS} = 0 V		1.9		V

All measurements were done with substrate shorted to source.

Thermal Characteristics

		TYP	UNIT
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.45	˚C/W
$R_{\theta JB}$	Thermal Resistance, Junction to Board	3.9	˚C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1)	45	˚C/W

Note 1: $R_{\theta JA}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.
See http://epc-co.com/epc/documents/product-training/Appnote_Thermal_Performance_of_eGaN_FETs.pdf for details.

Dynamic Characteristics (T_J = 25˚C unless otherwise stated)						
PARAMETER		**TEST CONDITIONS**	**MIN**	**TYP**	**MAX**	**UNIT**
C_{ISS}	Input Capacitance	V_{DS} = 120 V, V_{GS} = 0 V		1160	1400	pF
C_{RSS}	Reverse Transfer Capacitance			6		
C_{OSS}	Output Capacitance			480	720	
$C_{OSS(ER)}$	Effective Output Capacitance, Energy Related (Note 2)	V_{DS} = 0 to 120 V, V_{GS} = 0 V		670		
$C_{OSS(TR)}$	Effective Output Capacitance, Time Related (Note 3)			900		
R_G	Gate Resistance			0.5		Ω
Q_G	Total Gate Charge	V_{DS} = 120 V, V_{GS} = 5 V, I_D = 25 A		12	15	nC
Q_{GS}	Gate-to-Source Charge	V_{DS} = 120 V, I_D = 25 A		3.8		
Q_{GD}	Gate-to-Drain Charge			3.2		
$Q_{G(TH)}$	Gate Charge at Threshold			2.8		
Q_{OSS}	Output Charge	V_{DS} = 120 V, V_{GS} = 0 V		90	135	
Q_{RR}	Source-to-Drain Recovery Charge			0		

Note 2: $C_{OSS(ER)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 80% BV_{DSS}.
Note 3: $C_{OSS(TR)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 80% BV_{DSS}.

Figure 1: Typical Output Characteristics at 25°C

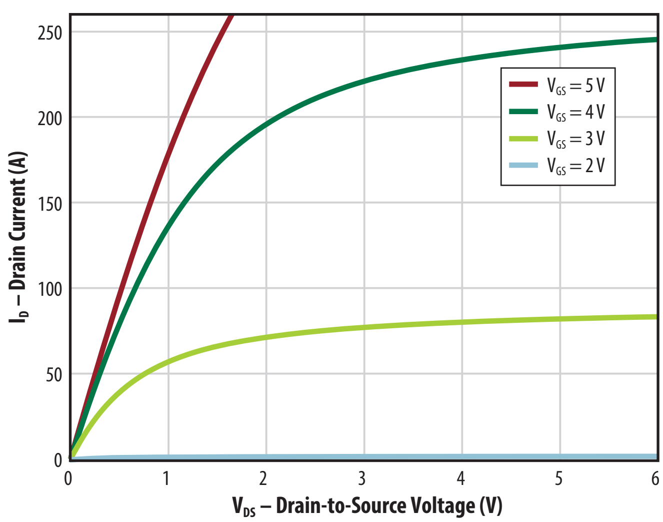


Figure 2: Transfer Characteristics

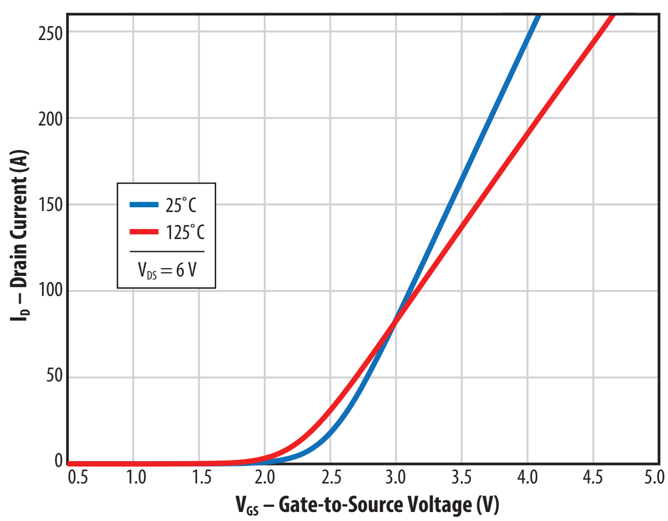


Figure 3: $R_{DS(on)}$ vs. V_{GS} for Various Drain Currents

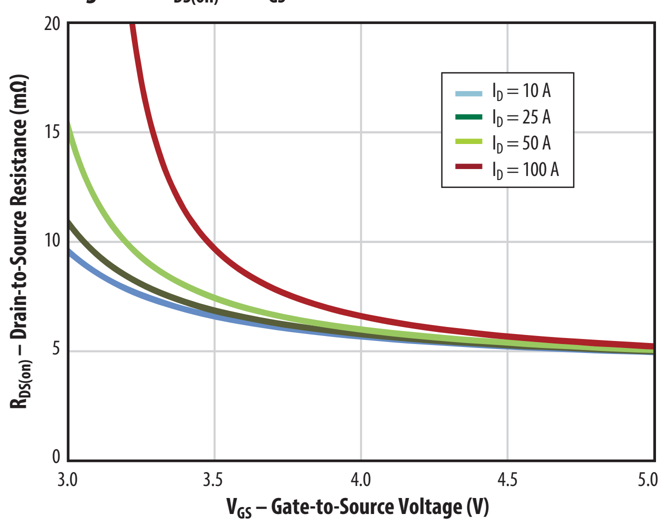


Figure 4: $R_{DS(on)}$ vs. V_{GS} for Various Temperatures

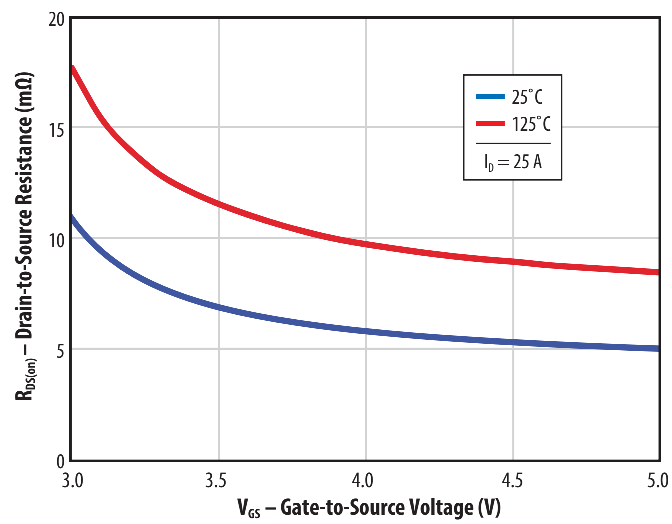


Figure 5a: Capacitance (Linear Scale)

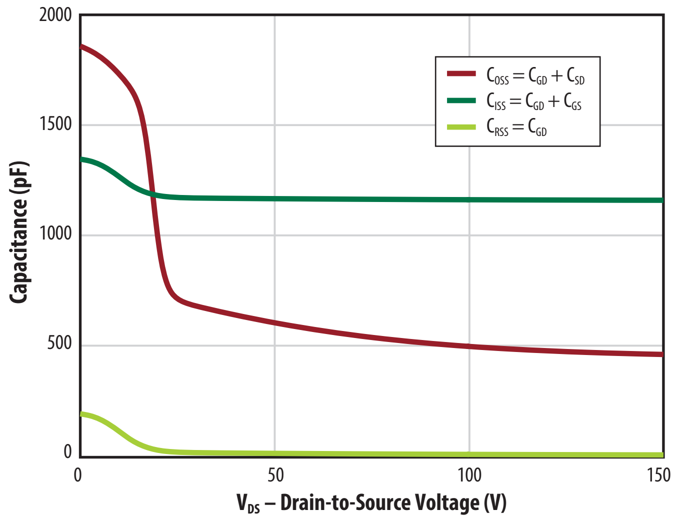


Figure 5b: Capacitance (Log Scale)

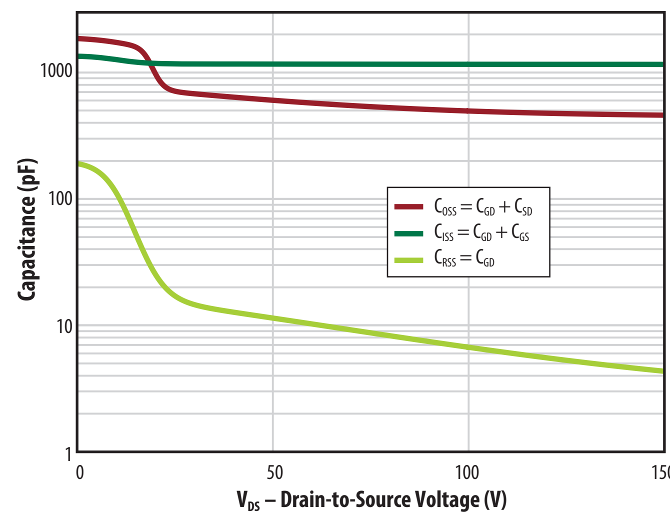


Figure 6: Gate Charge

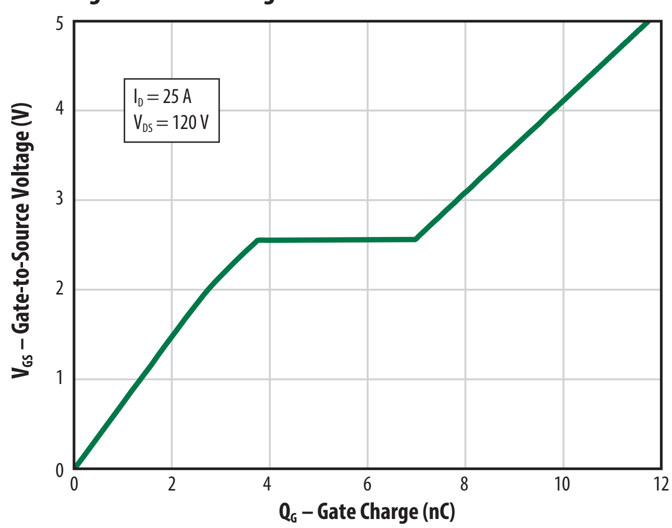


Figure 7: Reverse Drain-Source Characteristics

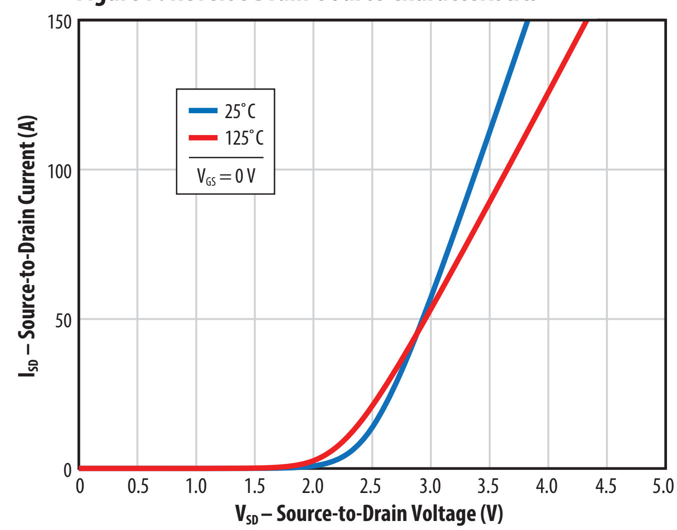


Figure 8: Normalized On-State Resistance vs. Temperature

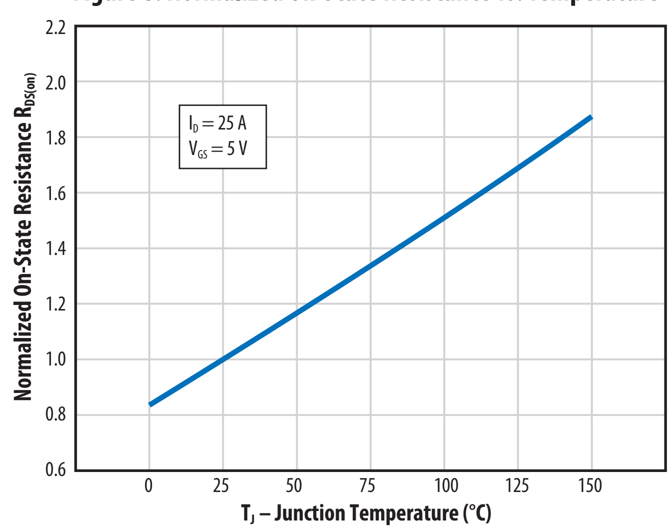
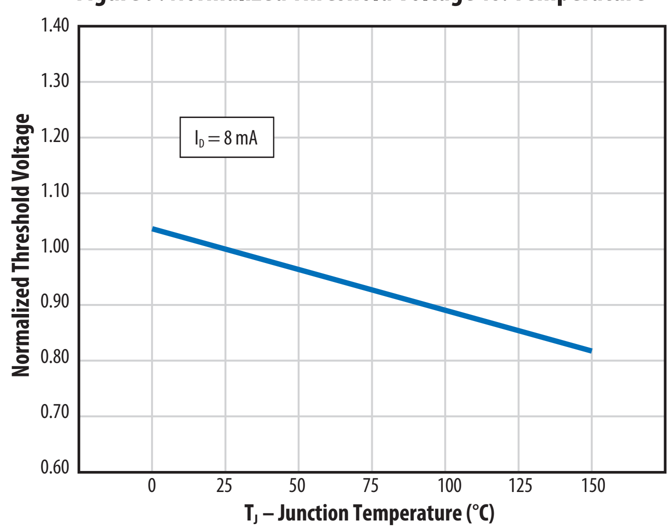


Figure 9: Normalized Threshold Voltage vs. Temperature



All measurements were done with substrate shortened to source. TJ= 25°C unless otherwise stated.

Figure 10: Gate Leakage Current

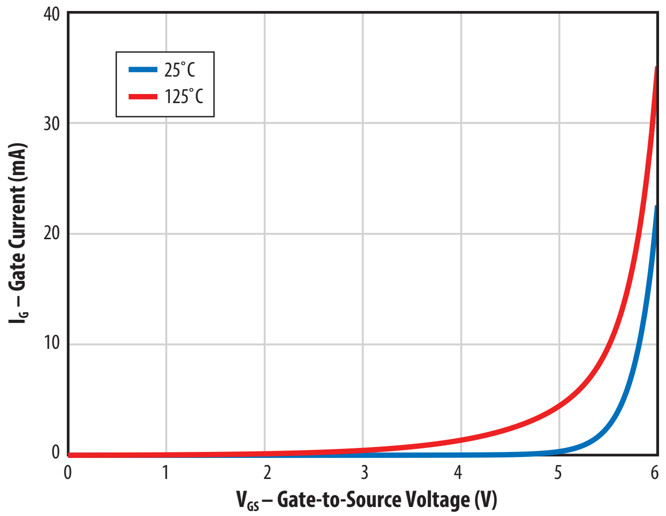


Figure 11: Safe Operating Area

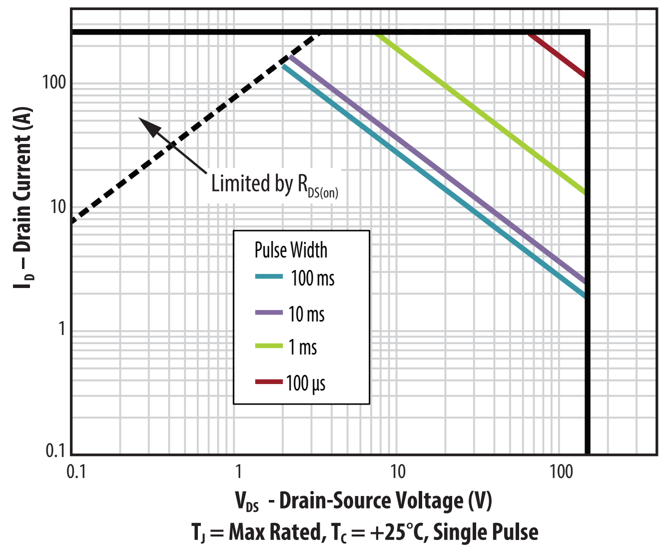
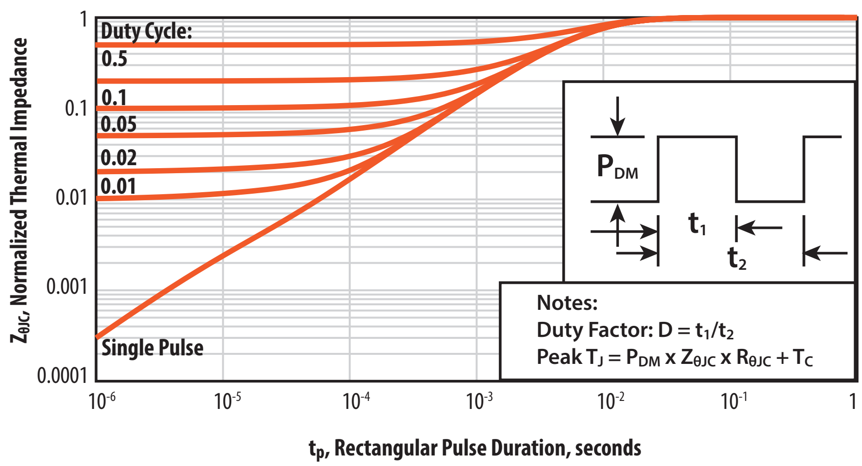
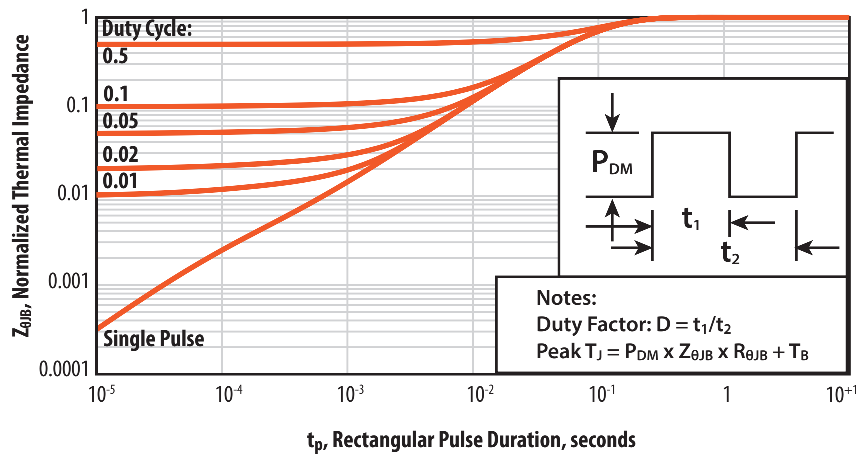


Figure 12: Transient Thermal Response Curves

Junction-to-Case

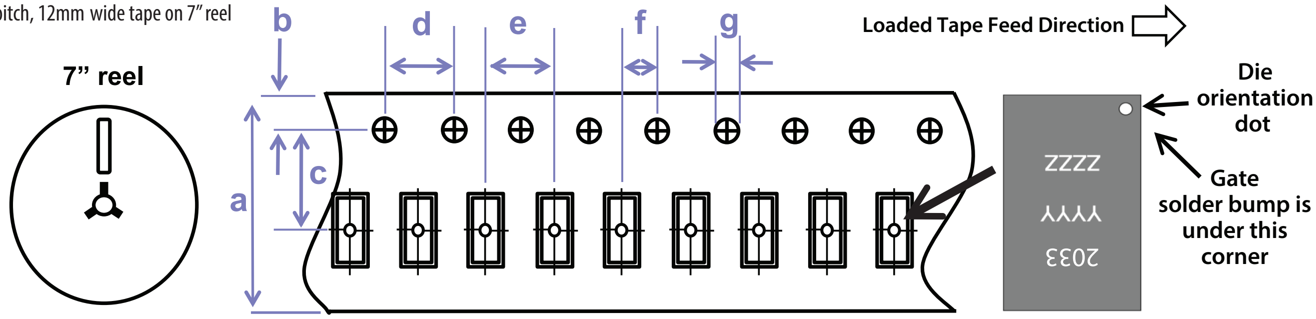


Junction-to-Board



TAPE AND REEL CONFIGURATION

4mm pitch, 12mm wide tape on 7" reel

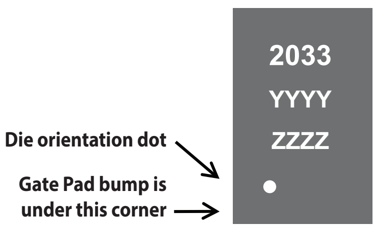


Die is placed into pocket solder bump side down (face side down)

	EPC2033 (note 1)		
Dimension (mm)	target	min	max
a	12.00	11.70	12.30
b	1.75	1.65	1.85
c (see note)	5.50	5.45	5.55
d	4.00	3.90	4.10
e	4.00	3.90	4.10
f (see note)	2.00	1.95	2.05
g	1.50	1.50	1.60

Note 1: MSL 1 (moisture sensitivity level 1) classified according to IPC/JEDEC industry standard.
Note 2: Pocket position is relative to the sprocket hole measured as true position of the pocket, not the pocket hole.

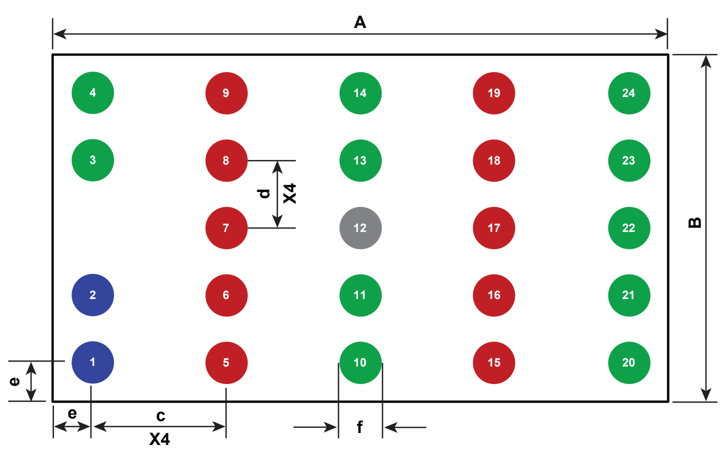
DIE MARKINGS



Part Number	Laser Marking		
	Part # Marking Line 1	Lot_Date Code Marking Line 2	Lot_Date Code Marking Line 3
EPC2033	2033	YYYY	ZZZZ

DIE OUTLINE

Solder Bump View



DIM	Micrometers		
	MIN	Nominal	MAX
A	4570	4600	4630
B	2570	2600	2630
c	1000	1000	1000
d	500	500	500
e	285	300	315
f	332	369	406

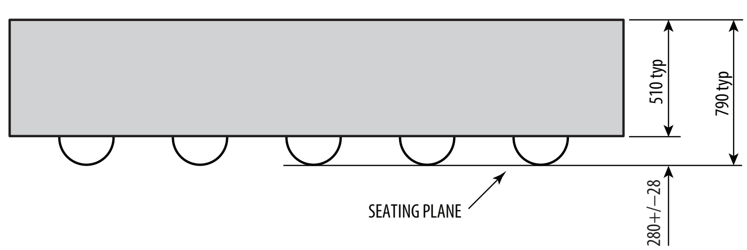
Pads 1 and 2 are Gate;

Pads 5, 6, 7, 8, 9, 15, 16, 17, 18, 19 are Drain;

Pads 3, 4, 10, 11, 13, 14, 20, 21, 22, 23, 24 are Source;

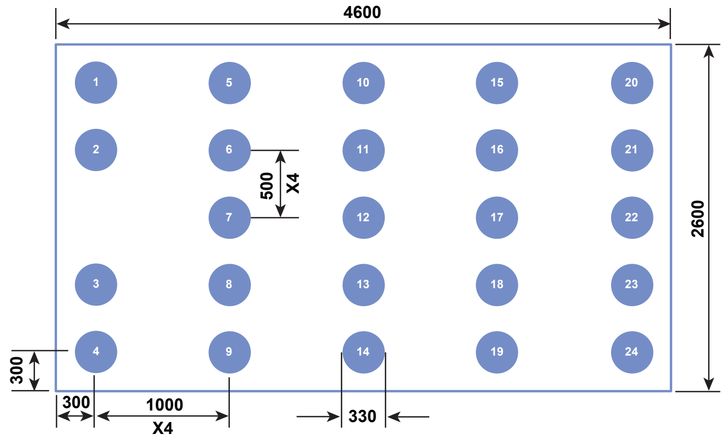
Pad 12 is Substrate

Side View



RECOMMENDED LAND PATTERN

(units in µm)



Land pattern is solder mask defined

Solder mask opening is 330 µm

It is recommended to have on-Cu trace PCB vias

Pads 1 and 2 are Gate;

Pads 5, 6, 7, 8, 9, 15, 16, 17, 18, 19 are Drain;

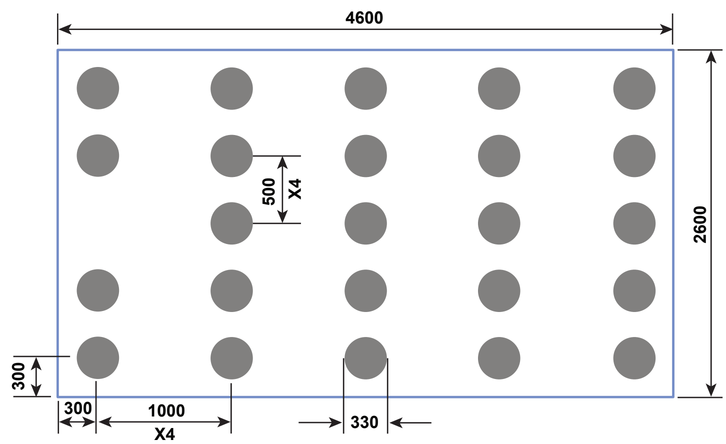
Pads 3, 4, 10, 11, 13, 14, 20, 21, 22, 23, 24 are Source;

Pad 12 is Substrate

RECOMMENDED STENCIL DRAWING

(units in µm)

Option 1 : Intended for use with SAC305 Type 4 solder.



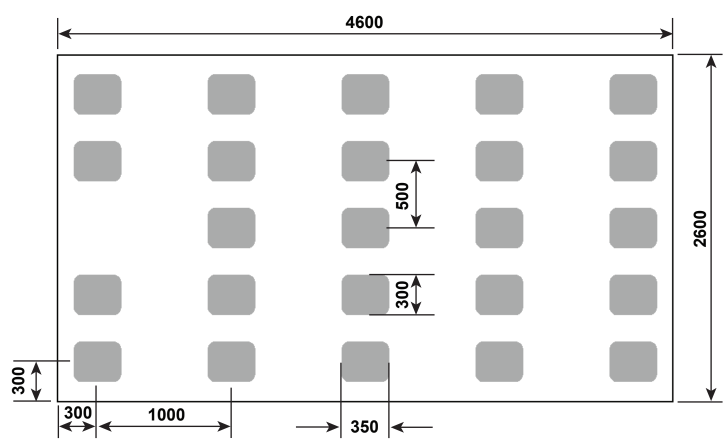
Recommended stencil should be 4mil (100 µm) thick, must be laser cut, openings per drawing.

Additional assembly resources available at http://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx

RECOMMENDED STENCIL DRAWING

(units in µm)

Option 2 : Intended for use with SAC305 Type 3 solder.



Recommended stencil should be 4mil (100 µm) thick, must be laser cut, openings per drawing.

Additional assembly resources available at http://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx

Information subject to change without notice.

Revised December, 2016